


GTXO-C86 - 2.5 & 3.3V (VC)TCXO CMOS High Temp					
Sub-Assembly	Material	Substance	CAS No	Mass (mg)	Sub-Assembly % by mass
Adhesive	Adhesive	Epoxy resin trade secret	0	5.000	100.00
Gold Bumps	gold	Au	7440-57-5	0.100	100.00
IC	Silicon substrate	Si	7440-21-3	1.994	99.70
	Silicon substrate	Al	7429-90-5	0.006	0.30
TP Base	Au plate	Au	7440-57-5	0.490	1.17
	Ceramic	Al ₂ O ₃	1344-28-1	34.335	81.75
	Ceramic	Cr ₂ O ₃	1308-38-9	0.763	1.82
	Ceramic	Mo	7439-98-7	0.763	1.82
	Ceramic	SiO ₂	14808-60-7	2.289	5.45
	Metallisation	W	7440-33-7	3.180	7.57
	Ni plate	Ni	7440-02-0	0.180	0.43
Tin paste	solder alloy	Sn	7440-31-5	0.846	84.60
	solder alloy	Sb	7440-36-0	0.044	4.40
	solder alloy	Flux trade secret	0	0.110	11.00
XX Crystal	Adhesive	Ag	7440-22-4	0.640	1.27
	Adhesive	SiO ₂	14808-60-7	0.080	0.16
	Adhesive	Epoxy resin trade secret	0	0.080	0.16
	Base Ceramic	Al ₂ O ₃	1344-28-1	22.896	45.43
	Base Ceramic	Cr ₂ O ₃	1308-38-9	0.509	1.01
	Base Ceramic	Mo	7439-98-7	0.509	1.01
	Base Ceramic	SiO ₂	14808-60-7	1.526	3.03
	Base Metallisation	W	7440-33-7	4.780	9.48
	Base Plate Au	Au	7440-57-5	0.210	0.42
	Base Plate Ni	Ni	7440-02-0	0.750	1.49
	Base Seal ring	Co	7440-48-4	1.031	2.05
	Base Seal ring	Fe	7439-89-6	3.037	6.03
	Base Seal ring	Ni	7440-02-0	1.662	3.30
	Base Solder	Ag	7440-22-4	1.008	2.00
	Base Solder	Cu	7440-50-8	0.412	0.82
	Blank	SiO ₂	14808-60-7	1.000	1.98
	Electrode material	Ni	7440-02-0	0.020	0.04
	Electrode material	Au	7440-57-5	0.180	0.36
	Kovar Lid	Fe	7439-89-6	5.050	10.02
	Kovar Lid	Ni	7440-02-0	2.659	5.28
Kovar Lid	Co	7440-48-4	1.709	3.39	
Lid Plate	Ni	7440-02-0	0.648	1.29	

Material Composition Data

Product: GTXO-C86

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Sub-Assembly	Material	Substance	CAS No	Mass (mg)	Sub-Assembly % by mass
				Total Mass:	100.496 mg
		 _____	John Hems Quality Manager Email: j.hems@golledge.com		